**TOSHIBA** 2SK2989

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOSVI)

# 2 S K 2 9 8 9

HIGH SPEED SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 120 \,\mathrm{m}\Omega$  (Typ.)

High Forward Transfer Admittance :  $|Y_{fS}| = 2.6 S$  (Typ.)

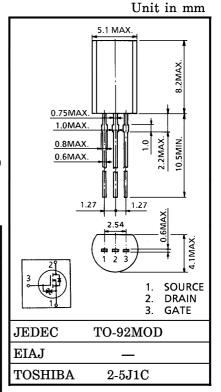
Low Leakage Current :  $I_{DSS} = 100 \,\mu\text{A} \, (V_{DS} = 50 \,\text{V})$ 

:  $V_{th} = 1.0 \sim 2.2 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{mA})$ Enhancement-Mode

#### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT		
Drain-Source Voltage	$ m V_{DSS}$	50	V		
Drain-Gate Voltage (R <sub>GS</sub> = $20 \text{ k}\Omega$ )		${ m v_{DGR}}$	50	V	
Gate-Source Voltage	$v_{GSS}$	±20	V		
Drain Current	DC	$I_{\mathbf{D}}$	5	A	
	Pulse	$I_{\mathrm{DP}}$	15		
Drain Power Dissipation	$P_{\mathbf{D}}$	0.9	W		
Channel Temperature		$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Range		$\mathrm{T_{stg}}$	-55~150	°C	

# INDUSTRIAL APPLICATIONS



#### THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	138	°C/W

This transistor is an electrostatic sensitive device. Please handle with caution.

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## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARAC	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	$I_{GSS}$	$V_{GS} = \pm 16  V,  V_{DS} = 0  V$	_	_	±10	$\mu$ A
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS} = 50  V, \ V_{GS} = 0  V$		_	100	$\mu$ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{ m D} = 10  { m mA}, \; { m V}_{ m GS} = 0  { m V}$	50	_	_	V
Gate Thresho	ld Voltage	$V_{ m th}$	$V_{\mathrm{DS}} = 10  \mathrm{V},  \mathrm{I}_{\mathrm{D}} = 1  \mathrm{mA}$	0.8	_	2.0	V
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	$V_{GS} = 4 \text{ V}, I_{D} = 1.3 \text{ A}$ $V_{GS} = 10 \text{ V}, I_{D} = 2.5 \text{ A}$		240 120	330 150	m $\Omega$
Forward Tran Admittance	nsfer	Y <sub>fs</sub>	$V_{ m DS} = 10 \  m V, \ I_{ m D} = 2.5 \  m A$	1.3	2.6	_	S
Input Capacit	ance	$C_{iss}$			145	_	pF
Reverse Transfer Capacitance		$C_{rss}$	$egin{aligned} { m V}_{ m DS} = 10  { m V}, \; { m V}_{ m GS} = 0  { m V} \ { m f} = 1  { m MHz} \end{aligned}$	_	25	_	
Output Capacitance		$C_{oss}$		_	75	_	
Switching Time	Rise Time	$t_{\mathbf{r}}$	$V_{GS} \stackrel{10 \text{ V}}{\underset{0 \text{ V}}{\text{ID}}} = 2.5 \text{ A}$ $V_{GS} \stackrel{10 \text{ V}}{\underset{0 \text{ V}}{\text{ID}}} = 2.5 \text{ A}$ $R_{L} = 10 \Omega$ $V_{DD} = 25 \text{ V}$	_	16	_	ns
	Turn-on Time	t <sub>on</sub>		_	23	_	
	Fall Time	$t_f$		-	27	_	115
	Turn-off Time	t <sub>off</sub>	$egin{aligned}  ext{VIN}:  ext{t}_{ ext{r}},  ext{t}_{ ext{f}} < 5   ext{ns}, \  ext{Duty} & \leq 1\%,  ext{t}_{ ext{W}} = 10  \mu  ext{s} \end{aligned}$		110	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 40 \text{ V}, V_{GS} = 10 \text{ V}$	_	6.5	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathrm{D}} = 5 \mathrm{A}$	_	5	_	"
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$		_	1.5	_	

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	5	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_		15	Α
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = 5 A$ , $V_{GS} = 0 V$	_	_	-1.5	V

#### **MARKING**

